

DEVELOPMENT OF ARGONNE MCP-PMT AND EXPLORING LAPPD APPLICATION FOR PARTICLE IDENTIFICATION





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DEVELOPMENT OF MCP-PMT FOR EIC-PID

Key Issue: Photodetectors

- Photo Detectors: The most important challenge is to provide a reliable highly-pixelated photodetector working at 2-3 Tesla. This problem is not yet solved.
 - Large-Area Picosecond PhotoDetector (LAPPD)
 - Promising but still not fully applicable for EIC needs.

Current focus at Argonne National Laboratory:

- Magnetic field tolerance
- Fine pixel readout
- Fast timing

Other requirement:

- QE uniformity
- Life time
- After pulse
- Stability etc...

LOW-COST FULL GLASS/FUSED SILICA DESIGN



- Full glass/fused silica design for mature fabrication process and low-cost;
- b) Fused silica (or borosilicate glass with wavelength shifter) window extending sensitivity down to UV range for better Cerenkov light detection;
- Newly developed 10 µm pore size
 MCPs for higher magnetic field tolerance and fast timing;
- d) Reduced spacing internal geometry further improves the magnetic field tolerance and timing resolution;
- e) Capacitively coupled electronic readout through glass/fused silica for custom readout scheme.



IMPROVEMENT OF ARGONNE MCP-PMT PERFORMANCE IN MAGNETIC FIELD



Babar and CLEO Magnets: 1.5T

- Optimization of biased voltages for both MCPs: version 1 -> 2
- Smaller pore size MCPs: version 2 -> 3
- Reduced spacing: version 3 -> 4
- Further improvement if needed:

Smaller pore size: 6 µm, version 4 -> 5 (future)

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DETAILED PARAMETERS AND PERFORMANCE OF ARGONNE MCP-PMT

ANL Version 4, 10 µm MCP-PMT with reduced spacing

Pore size	10 µm		\sim
Length to diameter ratio	60:1		
(L/d)			
Thickness	0.6 mm		t, = 394 ps
Open area ratio	70 %		FWHM = 649 ps
Bias angle	13º		
Window thickness	2.75 mm	-20	
		-25 27.5 30	32.5 35
Spacing 1	2.25 mm	Time (ns)	
Spacing 2	0.7 mm		
Spacing 3	1.1 mm	g120	Entries 1
Shims	0.3 mm		Mean 2 Std Dev 8
Tile base thickness	2.75 mm		= 88.6 ps
Internal stack height	5.55 mm		= 34.9 ps
Total stack height	11.05 mm		
			< 100ps
Gain	2.0 × 10 ⁷		< 100ps
			אוטרוויט
Rise time	394 ps		
		B > 1.5 Tesla	
TTS RMS time resolution	88.6 ps		
TTS resolution	35 ps	0.0 0.3 0.6 0.9 1.2 1.5 -200 -100 0 100 200 Magnetic Field (Tesla)	Delay [ps]
Magnetic field tolerance	Over 1 5 T		
	Pore size Length to diameter ratio (L/d) Thickness Open area ratio Bias angle Window thickness Spacing 1 Spacing 2 Spacing 3 Shims Tile base thickness Internal stack height Total stack height Total stack height Total stack height	Pore size10 μmLength to diameter ratio60:1(L/d)-Thickness0.6 mmOpen area ratio70 %Bias angle13°Window thickness2.75 mmSpacing 12.25 mmSpacing 20.7 mmSpacing 31.1 mmShims0.3 mmTile base thickness2.75 mmInternal stack height5.55 mmTotal stack height11.05 mmGain2.0 × 107Rise time394 psTTS RMS time resolution88.6 psTTS resolution35 psMagnetic field toleranceOver 1 5 T	Pore size Length to diameter ratio (L/d)10 µm 60:1 (L/d)Thickness0.6 mm 70 % Bias angle13° 2.75 mmWindow thickness2.75 mmSpacing 1 Spacing 22.25 mm 0.3 mmSpacing 1 Shims2.25 mm 0.3 mmSpacing 2 Tile base thickness0.7 mm 2.75 mmGain Gain2.0 × 107 Tils resolutionGain TTS RMS time resolution2.0 × 107 35 psTTS RMS time resolution TTS resolution88.6 ps 35 psTTS RMS time resolution TTS resolution88.6 ps 35 ps

FINE PIXELATED READOUT THROUGH GLASS/FUSED SILICA ANODE

Argonne MCP stack (glass anode) in Fermilab test beam



4 different pixel sizes (2x2,3x3,4x4 and 5x5 mm²) implemented for testing





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POSITION RESOLUTION

Difference between the pad mean position (CG) and the track pointing



4 mm x 4 mm pixel as example

	X res (mm)	Y res (mm)
2x2 mm	1.4	1.7
3x3 mm	0.94	0.95
4x4 mm	0.81	0.76
5x5 mm	1.1	0.97

All resolutions ~1 mm with small pixels, reaching the requirements for EIC Cerenkov sub-systems.

- Potentially limited by track pointing resolution capability of MWPCs (1 mm pitch)
- 2x2 may be worse due to leakage of signals (poor containment since it is a smaller area)

CURRENT STATUS OF LAPPD COMMERCIALIZATION



Commercialization: 20x20 cm²

Different readout schemes

Gen I

Gen II





Stripline readout

Products Available



Capacitive coupling

Prototypes Available



Low temperature co-fire ceramic

Under development



EXPLORE APPLICATION OF LAPPDTM FOR NUCLEAR PHYSICS PARTICLE IDENTIFICATION

SoLID SoLID (Solenoidal Large Intensity Device) Light gas Cherenkov counter



EIC JLEIC: mRICH, hpDIRC and dRICH; TOPSiDE: gaseous-RICH



SOLID TELESCOPE CHERENKOV SETUP IN HALL C



CHERENKOV EXPERIMENT RESULTS WITH MAPMTS

The event rate for each quadrant is ~400 kHz, that is ~ 1.5 MHz rate per MaPMT, or **64 kHz/cm**².





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CHERENKOV EXPERIMENT RESULTS WITH LAPPD

MaPMT

0.81 M

Received LAPPD#41: Gen I

Event cut

Scin+ calo

Results

Window material	Fused silica
Readout anode	Inside stripline
Quantum Efficiency	Mean: 7.3%, Maximum: 11%
Gain	5.4×10 ⁶ with MCPs @ 975V
Time resolution	56 ps





LAPPD

7.1 M

JLab Hall C test shows that the LAPPD might work in the Hall C harsh environment to separate Cherenkov events. Needs high QE, pixelated LAPPDs for follow up testing.

PIXELATED GEN II LAPPD VALIDATION WITH SOLID PRE-R&D LIGHT GAS CHERENKOV PROTOTYPE (INSTALLED MAR. 15)





WLS coated Gen II LAPPD in tank box





25mm x 25 mm pixel size for Cherenkov counter, no imaging



EIC SCIENCE AND DETECTOR: TOPSIDE

Major Lab Initiative at ANL





▶ TOPSIDE

- (ongoing) Prove viability of concept through closed-loop simulation/ reconstruction.
- Optimize TOPSiDE for key EIC physics milestones
- Release software stack when implementation complete
- Support various YR sub-sections related to TOPSiDE



Argonne

EIC-PID FERMILAB BEAMLINE VALIDATION OF ARGONNE MCP-PMT & LAPPD WITH SUB-SYSTEMS

Projected timeline: **Spring 2020:** Argonne MCP-PMT & Gen II LAPPD for proof-of-concept sensor validation (pixel and zigzag schemes)

Spring 2021: Gen II LAPPD for mRICH module, dRICH, TOPSiDE-RICH prototype (if not ready, delay to Spring 2022)

Spring 2022: Delivery of Gen III HRPPD from Incom to EIC-PID

Spring 2023: Gen III HRPPD for hpDIRC



Imaging readout PCB design for Argonne MCP-PMT based on eRD6 GEM board with pixel (upper two) and zigzag (lower two) schemes.



SUMMARY

- R&D on optimization of LAPPD towards particle identification is on going, focusing on design development:
 - Magnetic field tolerance
 - Timing resolution
 - Pixel readout
- MCP-PMT with smaller pore size and reduced spacing exhibits significantly improved magnetic field tolerance and timing resolution.
- □ Fine pixel of 3x3 mm² with position resolution of ~ 1 mm was achieved with Argonne MCP stack (glass anode) in Fermilab test beam.
- Exploration of LAPPD application in Nuclear Physics particle identification are undergoing:
 - High rate background environment for SoLID Cherenkov
 - Fermilab Cherenkov imaging beamline test and sub-system validation
 - RICH with LAPPD @ TOPSiDE contributes to EIC-PID



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And many others ...

EIC PID Collaboration (eRD14): PID Consortium for an integrated program for Particle Identification (PID) at a future Electron-Ion Collider

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Thank you for your attention!

Questions?

